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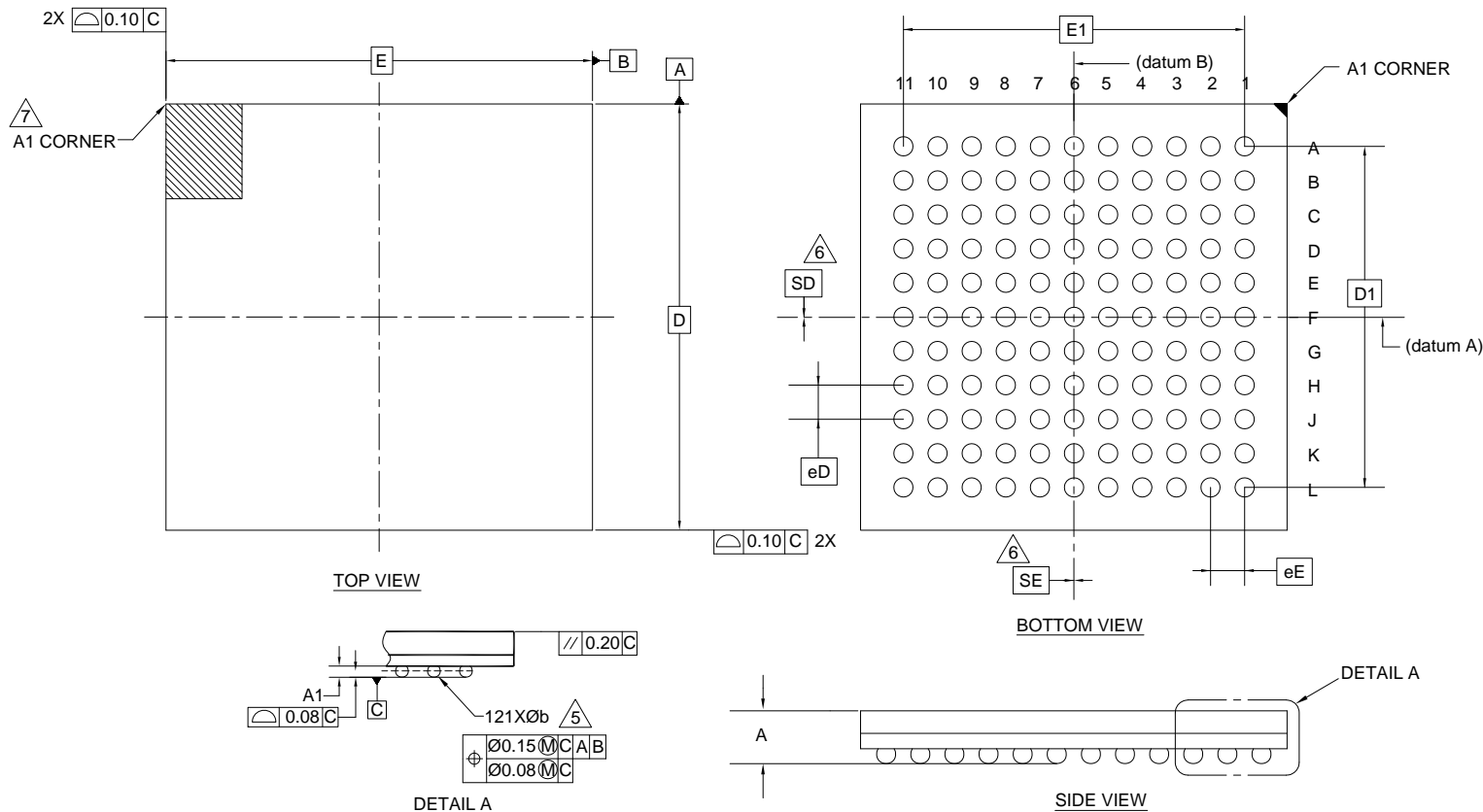
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.




SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.15	-	-
D	10.00 BSC		
E	10.00 BSC		
D1	8.00 BSC		
E1	8.00 BSC		
MD	11		
ME	11		
N	121		
\varnothing b	0.25	0.30	0.35
eD	0.80 BSC		
eE	0.80 BSC		
SD	0.00		
SE	0.00		

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- SOLDER BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
- "e" REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. N IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" OR "SE" = 0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" = eD/2 AND "SE" = eE/2.
- A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK METALIZED MARK, INDENTATION OR OTHER MEANS.
- "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED SOLDER BALLS.

CYPRESS
 Company Confidential
 TITLE PACKAGE OUTLINE, 121 BALL FBGA
 10.0X10.0X1.2 MM BK0AA/FB121/T4A121
 SPEC NO. 001-54471
 REV *F
 SCALE: TO FIT SHEET 1 OF 2

REVISIONS			
Rev	ECN No.	Orig. of change	Reason for Revision
**	2738843	MLA	NEW RELEASE
*A	2846357	MLA	CHANGE TO STANDARD TEMPLATE
*B	2964543	MLA	REVISE BALL HEIGHT DIMENSION AND ADD TOLERANCE TO PACKAGE HEIGHT
*C	3260577	MLA	REVISE BALL HEIGHT TO MATCH CML AND AMKOR CAPABILITY. ADD PKG WEIGHT
*D	3722826	MLA	CHANGED PKG WEIGHT FROM "0.2gr" TO "REFER TO PMDD SPEC"
*E	5112315	KOTA	ADD PACKAGE FBI121 AND T4A121.
*F	5788956	KOTA	CHANGED PACKAGE CODE FROM BK121A TO BK0AA.

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SPEC NO. 001-54471	REV *F
SCALE : TO FIT	SHEET 2 OF 2

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PACKAGE CODE(S)	BK0AA	FBI121	T4A121	DRAWN BY KOTA	DATE 28-JUN-17
				APPROVED BY GSHN	DATE 28-JUN-17